





Click here for the 3D model.

Dimensions	
L	4.5mm +/-0.3mm
W	3.2mm +/-0.3mm
т	3.3mm +/-0.4mm
В	0.6mm +/-0.35mm

Packaging Specifications			
Packaging	T&R, 180mm, Plastic Tape		
Packaging Quantity	500		

General Information	
Series	KONNEKT Auto COG
Style	KONNEKT
Description	SMD, MLCC, KONNEKT, Ultra-Stable, Class I
Features	High Density Packaging
RoHS	Yes
Termination	Tin
Qualifications	AEC-Q200
AEC-Q200	Yes
Component Weight	190 mg
Chip Size	1812-2
Shelf Life	78 Weeks
MSL	1

Specifications			
Capacitance	0.44 uF		
Measurement Condition	1 kHz 1.0Vrms		
Capacitance Tolerance	10%		
Voltage DC	50 VDC		
Dielectric Withstanding Voltage	125 VDC		
Temperature Range	-55/+125°C		
Temperature Coefficient	COG		
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C		
Dissipation Factor	0.1% 1 kHz 1.0Vrms		
Aging Rate	0% Loss/Decade Hour		
Insulation Resistance	1.136 GOhms		

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